

**Qualification Results Summary for  
LFCSP Package in NiPdAu Pre-plated Leadframe  
at STATS ChipPAC China (SCC)**

QUALIFICATION RESULTS			
Test	Specifications	Sample Size	Result
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	<b>3 x 77</b>	<b>PASS</b>
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	<b>3 x 11</b>	<b>PASS</b>
Low Temperature Storage (LTS)	JEDEC <i>JESD22-A119</i>	<b>3 x 77</b>	<b>PASS</b>
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	<b>3/Voltage</b>	<b>PASS ±1250V</b>

\*Preconditioned per JEDEC/IPC J-STD-020